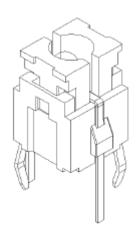




Document Number:

KH-PS1701-11

Product Specification



<u>P/N:</u>	_		Title:			
CLA606301D127			Lamp Switch			
Rev.	ECN	Release and Revision Description:	Prepared By /Date:	Checked By/Date:	Approved By/Date:	
A		New releasing	HQC 2018/10/24	LPH2018/10/24	LPH2018/10/24	



Product Specification

P/N:

DOC. No.:

KH-PS1701-11

Rev.:

Page: 2/9

Content

CLA606301D127

3
3
3
3
3
4
5
7~8
8
8
9



Product	Specification
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Lead-free welding : 255° C $\pm 5^{\circ}$ C $5s\pm 0.5s$;

DC12V / 50mA

P/N: DOC. No.:

KH-PS1701-11

Rev.:

Page: 3/9

1. Scope:

This Product Specification covers the requirement of Micro switch on product performance, test methods and quality assurance provisions.

CLA606301D127

2. Product Application:

The Switch is applied in all types of electrical appliances. Please let us know before using any of the products in the application not described abovev.

3. Technology Parameters:

Ambient Humidity: 45~85% R.H.; Operating Temperature Range: $-10^{\circ}\text{C} + 70^{\circ}\text{C}$; Storage Temperature Range: $-20^{\circ}\text{C} + 80^{\circ}\text{C}$; Suggested storage period: about 6 months

Normal Condition:

Ambient temperature: 20 ± 5 Relative humidity: $65\%\pm5\%$ R.H.; Air pressure: $86\sim101$ KPa; Contact Resistance: 100 m Ω Max; Operation Force: 150 ± 50 of

Operation Force: 150 ± 50 gf Solder Ability: Tim-lead soldering: $245\%\pm5\%$ 5s ±0.5 s;

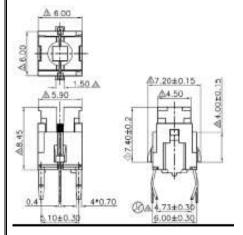
Withstand Soldering Temperature: Wave soldering: $260\pm5^{\circ}$ C 5 ± 0.5 s;

4. Rated Performance Requirements:

Rating:

Insulation Resistance: $\geqslant 100 \text{M}\Omega/\text{DC}\ 250 \text{V};$ Withstand Voltage: $250 \text{V}\ \text{AC}\ 1 \ \text{Minute};$ Mechanical Life: $100,000 \ \text{Cycles}.$

5. Profile Dimensions:





P/N:

DOC. No.:

CLA606301D127

KH-PS1701-11

Rev.:

Page: 4/9

6. Electrical Performance:

Item Description		Test Condition	Requirement	
6.1	Contact Resistance	Static load: (Operation force)x2, which is applied on the center of Switch stem. Be measured when the switch contact stabilization. Measurement tool: Contact resistance Meter. (1KHz, 20mV,5~50mA) Measured at low current (100mA or less).	100mΩ Max	
6.2	Insulation Resistance	Apply a Voltage of DC 250 V for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body.	100MΩ Min	
6.3	Dielectric withstanding voltage Apply a Voltage of AC250 V (50~60Hz) for 1 minute, according to the below method. (1) Between terminals. (2) Between terminal and Body.		No evidence of breakdown.	
6.4	Bouncing	Operation speed: 3~4 times/s Oscilloscope Switch Bouncing Test Circuit.	Before Life cycle: On:5ms MAX Off: 5ms MAX After Life cycle: On:10ms MAX Off 10ms MAX	



P/N:

DOC. No.: CLA606301D127 KH-PS1701-11

Rev.:

Page: 5/9

7. Mechanical Performance:

It	Description	Tes Condition	Requirement
7.1	Operation force	Operate the keystoke of the switch and then increase press strength gradually, Measured maximum operation force while the travel of the switch is full.	150±50gf
7.2	Travel	Operate the keystoke of the switch vertically, the travel distance of keystoke moving from its free position to maximum moving distance shall be measurement.	0.25±0.1mm
7.3	Static Strength	A static load of 3kgf shall be applied in the direction of button operation for a period of 60 seconds.	No damage (Electrical and mechanical)
7.4	Stem Pull Strength	Break by a pull force applied opposite to the direction of stem operation.	500gf Min



Product Specification			
P/N:	DOC. No.:	Rev.:	Page:
CLA606301D127	KH-PS1701-11	A	6/9

7.5	Shock	Measured by according to the below condition: (1) Acceleration: 80g accelerated speed (2) Cycles of test:3 cycles each in 6 directions, for a total of 18 cycles.	Shall meet No.6, 7.1, 7.2
7.6	Life Test	(1) 1 Weight:300gf(2) Operation speed: 60cycles/min(3) Push force: Maximum value of operation force.(4) Cycles: 100,000 times Min	Contact resistance: 500Ω Max Bouncing: 10ms Max Operation force and tactile force: Variation rate within $\pm 30\%$

8. Environmental Performance:

Item	Description	Test Condition	Requirement	
8.1	Cold test	 (1) Temperature: - 20±2°C (2) Duration of test: 96h (3) Take off a drop water (4) Standard conditions after test: 1 	Contact resistance: 200m Ω Max Shall meet : No. 6.2 to 6.4 No. 7.1 to 7.2	
8.2	Heat test	 (1) Temperature: 80±2°C (2) Duration of test: 96h (3) Take off a drop water (4) Standard conditions after test: 1h 	Contact resistance: 200m Ω Max Shall meet : No. 6.2 to 6.4 No. 7.1 to 7.2	



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P/N:	DOC. No.:	Rev.:	Page:	
CLA606301D127	KH-PS1701-11	A	7/9	

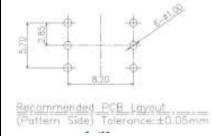
Nai	IN KAIHUA EL	LOTTIONIOO		
8.3	Temperature cycle	$(1) \ \text{Test cycles: 5 cycles} \\ (2) \ \text{Standard condition after test:1h} \\ \hline \\ $	Contact 200m Ω Shall me No. 6.2 No. 7.1	eet : to 6.4
8.4	Soldering heat test	Soldering area: 1/2 of PWB thickness. (PWB: T=1.6mm) Soldering temperature: 260±5℃ Soldering time: 5±0.5s	Appeara No abno	
8.5	Lead-tin soldering: Soldering temperature: $245\pm5^{\circ}$ C Solder Soldering time: 5 ± 0.5 s		area of	90% of surface immersed portion covered by solder.
8.6	Humidity test	 (1) Temperature: 40±2°C (2) relative humidity: 90~95% R.H. (3) Duration of test: 96h (4) Take off a drop water (5) Standard conditions after test: 1h 	Contact 250m Ω Shall me No. 6.2 No. 7.1	eet : to 6.4



Product Specification							
P/N:	DOC. No.:	_	Page:				
CLA606301D127	KH-PS1701-11	A	8/9				

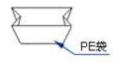
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8.7	Salt Spray	Apply the following for contact test): (1) Temperature: (2) Salt water densire) (3) Duration: 24hold (4) After test, the salt removed by running	$35{\pm}5^{\circ}\!$	` .	crack, n	osion spot o base pla Resistand	ate naked.
8.8	Withstand K ₂ S	Apply the following (1) Temperature: 35 (2) K ₂ S Density: 2% (3) Duration: 2 minut	±5℃ ;	est:	crack, n	osion spot o base pla Resistand	ate naked.

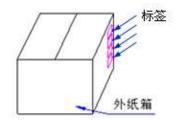
9. Recommended PCB Layout



10.Packaging:

Packaging type: Tray, 500Pcs/Bag, 10000Pcs/Carton.







P/N:

CLA606301D127

DOC. No.:

KH-PS1701-11

Rev.:

Page: 9/9

11.Precaution

11.1 Immersion Soldering condition

ITEM	CONDITION	
Preheat temperature	110℃ Max (Ambient temperature of soldering surface of P.W.B)	
Preheat time	60s, Max	
Area of flux	1/2 Max of PWB Thickness	
Temperature of solder	260±5℃ 260±5℃	
Time of immersion	5±0.5s 5±0.5s	
Number of soldering	2times Max (But should down heat of the first soldering)	
Printed wiring board	Single side copper-clad laminates	

- (1) After switches were soldered, please be careful not to clean switches with solvent
- (2) Under the condition of using soldering iron, soldering temperature shall be 350°C±5°C with 3±0.5s.

11.2 Notes

- (1) Please be cautious not to give excessive static load or shock to switches.
- (2) Please be careful not to stack up P. W. B. after switches were soldered.
- (3) Preservation under high temperature and high humidity or corrosive gas should be avoided Especially. When you need to preserve for a long period, do not open the carton.
- (4) The standard storage period is 3 months, with maximum up to 6months, preferably to be used as soon as possible. After opening the package, you should put the remaining switches in a plastic bag to prevent from damp and corrosive gas.
- (5) This Product Specification is considered as the technical agreement on product between the receiving customer and Kailh. Any information on Product Catalogue which is in conflict with or different from the corresponding information of this document is considered as invalid.
- (6) It will be considered that customer already confirmed and accepted this specification if customer issue purchase order to us directly.
 - (7) If there is no order or no request for new specification after 1 year upon this specification is issued, the specification will be regarded as invalid.
 - (8) Products meet the ROHS & REACH environmental management substances control standards